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Wong(10) **Pub. No.: US 2024/0213040 A1**(43) **Pub. Date: Jun. 27, 2024**(54) **SYSTEMS AND APPARATUS FOR
SEMICONDUCTOR EQUIPMENT**(52) **U.S. Cl.**
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(2013.01)(71) Applicant: **ASM IP Holding B.V.**, Almere (NL)(72) Inventor: **Mun Peow Wong**, Phoenix, AZ (US)(57) **ABSTRACT**(21) Appl. No.: **18/391,815**(22) Filed: **Dec. 21, 2023****Related U.S. Application Data**(60) Provisional application No. 63/435,376, filed on Dec.
27, 2022.**Publication Classification**(51) **Int. Cl.**
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Various embodiments of the present technology may provide an apparatus for removing oxygen and moisture from a semiconductor system. The apparatus may be coupled to a wafer handling chamber and include a blower, a first air purifier, a second air purifier, and a particle filter. The first and second air purifiers may be coupled in parallel to each other and downstream from the blower. The particle filter may be coupled downstream from the first and second air purifiers. The wafer handling chamber may include a fan integrated within a lower region of the wafer handling chamber.

